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Details

Product Status	Active
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI, SPI
Peripherals	LVD, POR, PWM
Number of I/O	17
Program Memory Size	7.5KB (7.5K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	384 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 6x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/pro/item?MUrl=&PartUrl=mc908gr8acdwe

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Memory

Addr.	Register Name		Bit 7	6	5	4	3	2	1	Bit 0
\$0018	SCI Data Register (SCDR) See page 154.	Read:	R7	R6	R5	R4	R3	R2	R1	R0
		Write:	T7	T6	T5	T4	T3	T2	T1	T0
		Reset:	Unaffected by reset							
\$0019	SCI Baud Rate Register (SCBR) See page 154.	Read:			SCP1	SCP0	R	SCR2	SCR1	SCR0
		Write:								
		Reset:	0	0	0	0	0	0	0	0
\$001A	Keyboard Status and Control Register (INTKBSCR) See page 103.	Read:	0	0	0	0	KEYF	0	IMASKK	MODEK
		Write:						ACKK		
		Reset:	0	0	0	0	0	0	0	0
\$001B	Keyboard Interrupt Enable Register (INTKBIER) See page 104.	Read:					KBIE3	KBIE2	KBIE1	KBIE0
		Write:								
		Reset:	0	0	0	0	0	0	0	0
\$001C	Timebase Module Control Register (TBCR) See page 197.	Read:	TBIF	TBR2	TBR1	TBR0	0	TBIE	TBON	R
		Write:					TACK			
		Reset:	0	0	0	0	0	0	0	0
\$001D	IRQ Status and Control Register (INTSCR) See page 98.	Read:	0	0	0	0	IRQF	0	IMASK	MODE
		Write:						ACK		
		Reset:	0	0	0	0	0	0	0	0
\$001E	Configuration Register 2 (CONFIG2) ⁽¹⁾ See page 75.	Read:	0	0	0	0	0	0	OSC-STOPENB	SCIBDSRC
		Write:								
		Reset:	0	0	0	0	0	0	0	0
\$001F	Configuration Register 1 (CONFIG1) ⁽¹⁾ See page 76.	Read:	COPRS	LVISTOP	LVIRSTD	LVIPWRD	LVI5OR3 (Note 1)	SSREC	STOP	COPD
		Write:								
		Reset:	0	0	0	0	0	0	0	0

1. One-time writable register after each reset, except LVI5OR3 bit. LVI5OR3 bit is only reset via POR (power-on reset).

\$0020	Timer 1 Status and Control Register (T1SC) See page 209.	Read:	TOF	TOIE	TSTOP	0	0	PS2	PS1	PS0
		Write:	0			TRST				
		Reset:	0	0	1	0	0	0	0	0
\$0021	Timer 1 Counter Register High (T1CNTH) See page 210.	Read:	Bit 15	14	13	12	11	10	9	Bit 8
		Write:								
		Reset:	0	0	0	0	0	0	0	0


 = Unimplemented R = Reserved U = Unaffected

Figure 2-2. Control, Status, and Data Registers (Sheet 3 of 7)

3.3.3 Conversion Time

Conversion starts after a write to the ADC status and control register (ADSCR). One conversion will take between 16 and 17 ADC clock cycles. The ADIVx and ADCLK bits should be set to provide a 1-MHz ADC clock frequency.

$$\text{Conversion time} = \frac{16 \text{ to } 17 \text{ ADC cycles}}{\text{ADC frequency}}$$

Number of bus cycles = conversion time × bus frequency

3.3.4 Conversion

In continuous conversion mode, the ADC data register will be filled with new data after each conversion. Data from the previous conversion will be overwritten whether that data has been read or not.

Conversions will continue until the ADCO bit is cleared. The COCO bit is set after the first conversion and will stay set until the next read of the ADC data register.

In single conversion mode, conversion begins with a write to the ADSCR. Only one conversion occurs between writes to the ADSCR.

When a conversion is in process and the ADSCR is written, the current conversion data should be discarded to prevent an incorrect reading.

3.3.5 Accuracy and Precision

The conversion process is monotonic and has no missing codes.

3.4 Interrupts

When the AIEN bit is set, the ADC module is capable of generating CPU interrupts after each ADC conversion. A CPU interrupt is generated if the COCO bit is at 0. The COCO bit is not used as a conversion complete flag when interrupts are enabled.

3.5 Low-Power Modes

The WAIT and STOP instruction can put the MCU in low power-consumption standby modes.

3.5.1 Wait Mode

The ADC continues normal operation during wait mode. Any enabled CPU interrupt request from the ADC can bring the MCU out of wait mode. If the ADC is not required to bring the MCU out of wait mode, power down the ADC by setting ADCH4–ADCH0 bits in the ADC status and control register before executing the WAIT instruction.

3.5.2 Stop Mode

The ADC module is inactive after the execution of a STOP instruction. Any pending conversion is aborted. ADC conversions resume when the MCU exits stop mode after an external interrupt. Allow one conversion cycle to stabilize the analog circuitry.

3.7.2 ADC Data Register

One 8-bit result register, ADC data register (ADR), is provided. This register is updated each time an ADC conversion completes.

Address: \$003D

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	AD7	AD6	AD5	AD4	AD3	AD2	AD1	AD0
Write:								
Reset:	0	0	0	0	0	0	0	0


 = Unimplemented

Figure 3-4. ADC Data Register (ADR)

3.7.3 ADC Clock Register

The ADC clock register (ADCLK) selects the clock frequency for the ADC.

Address: \$003E

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	ADIV2	ADIV1	ADIV0	ADICLK	0	0	0	0
Write:								
Reset:	0	0	0	0	0	0	0	0


 = Unimplemented

Figure 3-5. ADC Clock Register (ADCLK)

ADIV2–ADIV0 — ADC Clock Prescaler Bits

ADIV2–ADIV0 form a 3-bit field which selects the divide ratio used by the ADC to generate the internal ADC clock. Table 3-2 shows the available clock configurations. The ADC clock should be set to approximately 1 MHz.

Table 3-2. ADC Clock Divide Ratio

ADIV2	ADIV1	ADIV0	ADC Clock Rate
0	0	0	ADC input clock ÷ 1
0	0	1	ADC input clock ÷ 2
0	1	0	ADC input clock ÷ 4
0	1	1	ADC input clock ÷ 8
1	X ⁽¹⁾	X ⁽¹⁾	ADC input clock ÷ 16

1. X = Don't care

ADICLK — ADC Input Clock Select Bit

ADICLK selects either the bus clock or the oscillator output clock (CGMXCLK) as the input clock source to generate the internal ADC clock. Reset selects CGMXCLK as the ADC clock source.

1 = Internal bus clock

0 = Oscillator output clock (CGMXCLK)

The following conditions apply when in manual mode:

- \overline{ACQ} is a writable control bit that controls the mode of the filter. Before turning on the PLL in manual mode, the \overline{ACQ} bit must be clear.
- Before entering tracking mode ($\overline{ACQ} = 1$), software must wait a given time, t_{ACQ} (see 4.8 Acquisition/Lock Time Specifications), after turning on the PLL by setting PLLON in the PLL control register (PCTL).
- Software must wait a given time, t_{AL} , after entering tracking mode before selecting the PLL as the clock source to CGMOUT (BCS = 1).
- The LOCK bit is disabled.
- CPU interrupts from the CGM are disabled.

4.3.6 Programming the PLL

The following procedure shows how to program the PLL.

NOTE

The round function in the following equations means that the real number should be rounded to the nearest integer number.

1. Choose the desired bus frequency, f_{BUSDES} .
2. Calculate the desired VCO frequency (four times the desired bus frequency).

$$f_{VCLKDES} = 4 \times f_{BUSDES}$$

3. Choose a practical PLL (crystal) reference frequency, f_{RCLK} , and the reference divider, R. Typically, the reference crystal is 4 MHz and R = 1.

Frequency errors to the PLL are corrected at a rate of f_{RCLK}/R . For stability and lock time reduction, this rate must be as fast as possible. The VCO frequency must be an integer multiple of this rate. The relationship between the VCO frequency, f_{VCLK} , and the reference frequency, f_{RCLK} , is

$$f_{VCLK} = \frac{2^P N}{R} (f_{RCLK})$$

P, the power of two multiplier, and N, the range multiplier, are integers.

In cases where desired bus frequency has some tolerance, choose f_{RCLK} to a value determined either by other module requirements (such as modules which are clocked by CGMXCLK), cost requirements, or ideally, as high as the specified range allows. See Chapter 19 Electrical Specifications. Choose the reference divider, R = 1. After choosing N and P, the actual bus frequency can be determined using equation in 2 above.

When the tolerance on the bus frequency is tight, choose f_{RCLK} to an integer divisor of f_{BUSDES} , and R = 1. If f_{RCLK} cannot meet this requirement, use the following equation to solve for R with practical choices of f_{RCLK} , and choose the f_{RCLK} that gives the lowest R.

$$R = \text{round} \left[R_{MAX} \times \left\{ \left(\frac{f_{VCLKDES}}{f_{RCLK}} \right) - \text{integer} \left(\frac{f_{VCLKDES}}{f_{RCLK}} \right) \right\} \right]$$

4.5.4 PLL Multiplier Select Register Low

The PLL multiplier select register low (PMSL) contains the programming information for the low byte of the modulo feedback divider.

Address: \$0038

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	MUL7	MUL6	MUL5	MUL4	MUL3	MUL2	MUL1	MUL0
Write:								
Reset:	0	1	0	0	0	0	0	0

Figure 4-7. PLL Multiplier Select Register Low (PMSL)

NOTE

For applications using 1–8 MHz reference frequencies, this register must be reprogrammed before enabling the PLL. The reset value of this register will cause applications using 1–8 MHz reference frequencies to become unstable if the PLL is enabled without programming an appropriate value. The programmed value must not allow the VCO clock to exceed 32 MHz. See 4.3.6 Programming the PLL for detailed instructions on choosing the proper value for PMSL.

MUL7–MUL0 — Multiplier Select Bits

These read/write bits control the low byte of the modulo feedback divider that selects the VCO frequency multiplier, N. (See 4.3.3 PLL Circuits and 4.3.6 Programming the PLL.) MUL7–MUL0 cannot be written when the PLLON bit in the PCTL is set. A value of \$0000 in the multiplier select registers configures the modulo feedback divider the same as a value of \$0001. Reset initializes the register to \$40 for a default multiply value of 64.

NOTE

The multiplier select bits have built-in protection such that they cannot be written when the PLL is on (PLLON = 1).

4.5.5 PLL VCO Range Select Register

The PLL VCO range select register (PMRS) contains the programming information required for the hardware configuration of the VCO.

Address: \$003A

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	VRS7	VRS6	VRS5	VRS4	VRS3	VRS2	VRS1	VRS0
Write:								
Reset:	0	1	0	0	0	0	0	0

Figure 4-8. PLL VCO Range Select Register (PMRS)

VRS7–VRS0 — VCO Range Select Bits

These read/write bits control the hardware center-of-range linear multiplier L which, in conjunction with E (see 4.3.3 PLL Circuits, 4.3.6 Programming the PLL, and 4.5.1 PLL Control Register), controls the hardware center-of-range frequency, f_{VRS} . VRS7–VRS0 cannot be written when the PLLON bit in the PCTL is set. (See 4.3.7 Special Programming Exceptions.) A value of \$00 in the VCO range select

LVI5OR3 — LVI 5-V or 3-V Operating Mode Bit

LVI5OR3 selects the voltage operating mode of the LVI module (see Chapter 11 Low-Voltage Inhibit (LVI)). The voltage mode selected for the LVI should match the operating V_{DD} (see Chapter 19 Electrical Specifications) for the LVI's voltage trip points for each of the modes.

1 = LVI operates in 5-V mode

0 = LVI operates in 3-V mode

NOTE

The LVI5OR3 bit is cleared by a power-on reset (POR) only. Other resets will leave this bit unaffected.

SSREC — Short Stop Recovery Bit

SSREC enables the CPU to exit stop mode with a delay of 32 CGMXCLK cycles instead of a 4096-CGMXCLK cycle delay.

1 = Stop mode recovery after 32 CGMXCLK cycles

0 = Stop mode recovery after 4096 CGMXCLK cycles

NOTE

Exiting stop mode by an LVI reset will result in the long stop recovery.

If the system clock source is an external crystal and the OSCSTOPENB configuration bit is not set, the oscillator will be disabled during stop mode. The short stop recovery does not provide enough time for oscillator stabilization and for this reason the SSREC bit should not be set.

The system stabilization time for power-on reset and long stop recovery (both 4096 CGMXCLK cycles) gives a delay longer than the LVI enable time for these startup scenarios. There is no period where the MCU is not protected from a low-power condition. However, when using the short stop recovery configuration option, the 32-CGMXCLK delay must be greater than the LVI's turn on time to avoid a period in startup where the LVI is not protecting the MCU.

STOP — STOP Instruction Enable Bit

STOP enables the STOP instruction.

1 = STOP instruction enabled

0 = STOP instruction treated as illegal opcode

COPD — COP Disable Bit

COPD disables the COP module. See Chapter 6 Computer Operating Properly (COP) Module.

1 = COP module disabled

0 = COP module enabled

Chapter 14

System Integration Module (SIM)

14.1 Introduction

This section describes the system integration module (SIM). Together with the central processor unit (CPU), the SIM controls all microcontroller unit (MCU) activities. A block diagram of the SIM is shown in Figure 14-1. Table 14-1 is a summary of the SIM input/output (I/O) registers. The SIM is a system state controller that coordinates CPU and exception timing.

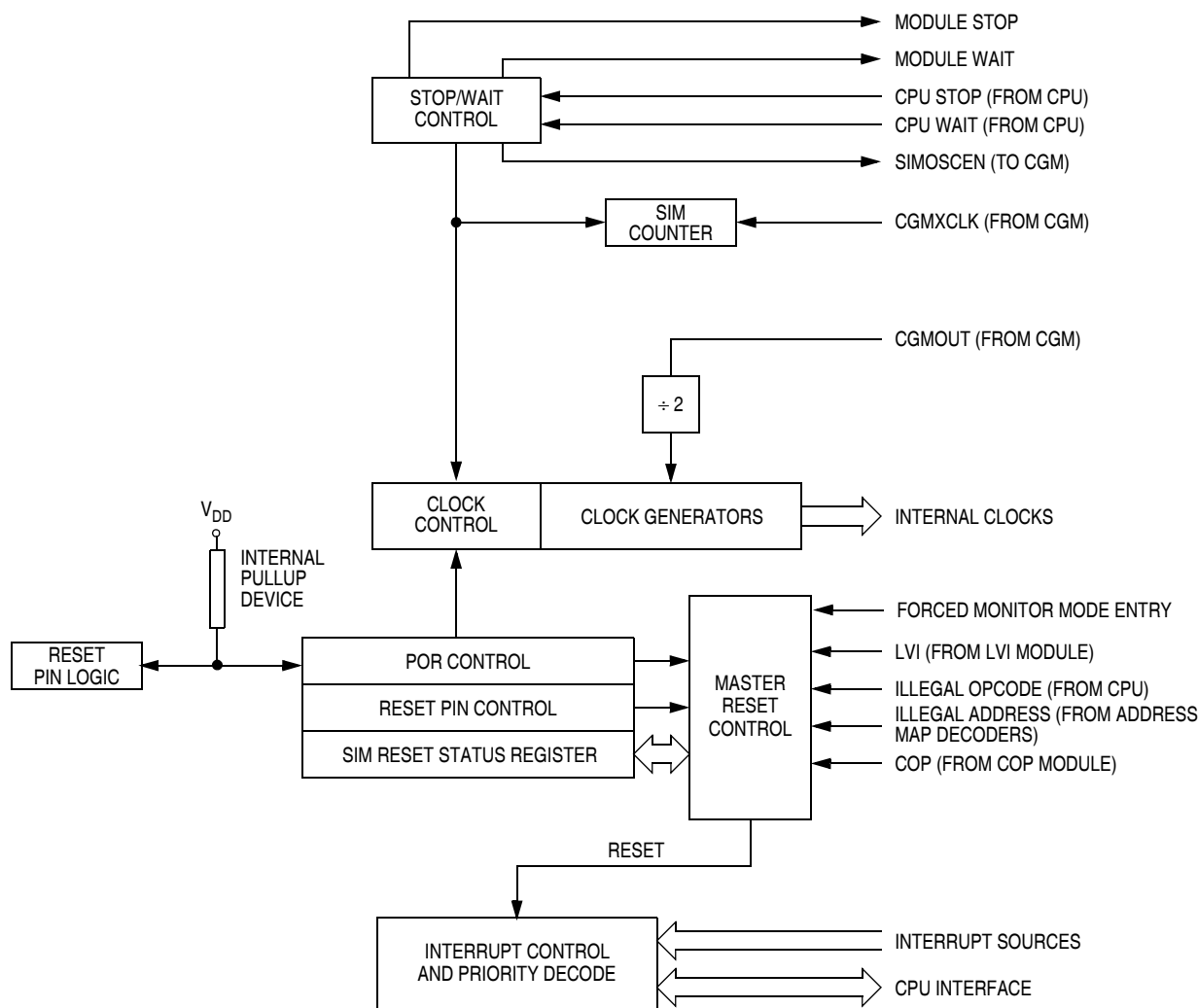


Figure 14-1. SIM Block Diagram

Protecting flags in break mode ensures that set flags will not be cleared while in break mode. This protection allows registers to be freely read and written during break mode without losing status flag information.

Setting the BCFE bit enables the clearing mechanisms. Once cleared in break mode, a flag remains cleared even when break mode is exited. Status flags with a 2-step clearing mechanism — for example, a read of one register followed by the read or write of another — are protected, even when the first step is accomplished prior to entering break mode. Upon leaving break mode, execution of the second step will clear the flag as normal.

14.6 Low-Power Modes

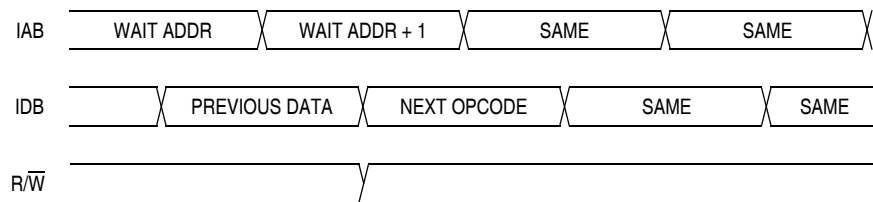
Executing the WAIT or STOP instruction puts the MCU in a low power- consumption mode for standby situations. The SIM holds the CPU in a non-clocked state. The operation of each of these modes is described in the following subsections. Both STOP and WAIT clear the interrupt mask (I) in the condition code register, allowing interrupts to occur.

14.6.1 Wait Mode

In wait mode, the CPU clocks are inactive while the peripheral clocks continue to run. Figure 14-15 shows the timing for wait mode entry.

A module that is active during wait mode can wakeup the CPU with an interrupt if the interrupt is enabled. Stacking for the interrupt begins one cycle after the WAIT instruction during which the interrupt occurred. In wait mode, the CPU clocks are inactive. Refer to the wait mode subsection of each module to see if the module is active or inactive in wait mode. Some modules can be programmed to be active in wait mode.

Wait mode also can be exited by a reset (or break in emulation mode). A break interrupt during wait mode sets the SIM break stop/wait bit, SBSW, in the SIM break status register (SBSR). If the COP disable bit, COPD, in the CONFIG1 register is 0, then the computer operating properly module (COP) is enabled and remains active in wait mode.



Note: Previous data can be operand data or the WAIT opcode, depending on the last instruction.

Figure 14-15. Wait Mode Entry Timing

Figure 14-16 and Figure 14-17 show the timing for WAIT recovery.

If the timebase functions are not required during stop mode, reduce power consumption by disabling the timebase module before executing the STOP instruction.

16.6 Timebase Control Register

The timebase has one register, the timebase control register (TBCR), which is used to enable the timebase interrupts and set the rate.

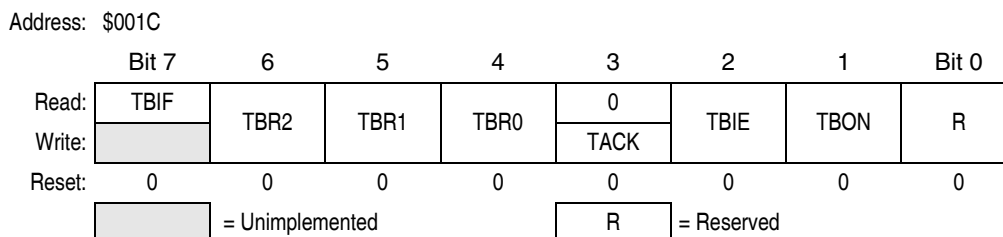


Figure 16-2. Timebase Control Register (TBCR)

TBIF — Timebase Interrupt Flag

This read-only flag bit is set when the timebase counter has rolled over.

1 = Timebase interrupt pending

0 = Timebase interrupt not pending

TBR2–TBR0 — Timebase Divider Selection Bits

These read/write bits select the tap in the counter to be used for timebase interrupts as shown in Table 16-1.

Table 16-1. Timebase Divider Selection

TBR2	TBR1	TBR0	Divider
0	0	0	32,768
0	0	1	8192
0	1	0	2048
0	1	1	128
1	0	0	64
1	0	1	32
1	1	0	16
1	1	1	8

NOTE

Do not change TBR2–TBR0 bits while the timebase is enabled (TBON = 1).

TACK— Timebase Acknowledge Bit

The TACK bit is a write-only bit and always reads as 0. Writing a 1 to this bit clears TBIF, the timebase interrupt flag bit. Writing a 0 to this bit has no effect.

1 = Clear timebase interrupt flag

0 = No effect

Timebase Module (TBM)

TBIE — Timebase Interrupt Enabled Bit

This read/write bit enables the timebase interrupt when the TBIF bit becomes set. Reset clears the TBIE bit.

1 = Timebase interrupt is enabled.

0 = Timebase interrupt is disabled.

TBON — Timebase Enabled Bit

This read/write bit enables the timebase. Timebase may be turned off to reduce power consumption when its function is not necessary. The counter can be initialized by clearing and then setting this bit. Reset clears the TBON bit.

1 = Timebase is enabled.

0 = Timebase is disabled and the counter initialized to 0s.

Address: T1MODH, \$0023 and T2MODH, \$002E

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	Bit 15	14	13	12	11	10	9	Bit 8
Write:								
Reset:	1	1	1	1	1	1	1	1

Figure 17-8. TIM Counter Modulo Register High (TMODH)

Address: T1MODL, \$0024 and T2MODL, \$002F

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	Bit 7	6	5	4	3	2	1	Bit 0
Write:								
Reset:	1	1	1	1	1	1	1	1

Figure 17-9. TIM Counter Modulo Register Low (TMODL)

NOTE

Reset the TIM counter before writing to the TIM counter modulo registers.

17.9.4 TIM Channel Status and Control Registers

Each of the TIM channel status and control registers:

- Flags input captures and output compares
- Enables input capture and output compare interrupts
- Selects input capture, output compare, or PWM operation
- Selects high, low, or toggling output on output compare
- Selects rising edge, falling edge, or any edge as the active input capture trigger
- Selects output toggling on TIM overflow
- Selects 0% and 100% PWM duty cycle
- Selects buffered or unbuffered output compare/PWM operation

Address: T1SC0, \$0025 and T2SC0, \$0030

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	CH0F	CH0IE	MS0B	MS0A	ELS0B	ELS0A	TOV0	CH0MAX
Write:	0							
Reset:	0	0	0	0	0	0	0	0

Figure 17-10. TIM Channel 0 Status and Control Register (TSC0)

Address: T1SC1, \$0028

	Bit 7	6	5	4	3	2	1	Bit 0
Read:	CH1F	CH1IE	0	MS1A	ELS1B	ELS1A	TOV1	CH1MAX
Write:	0							
Reset:	0	0	0	0	0	0	0	0

Figure 17-11. TIM Channel 1 Status and Control Register (TSC1)

19.10 Output Low-Voltage Characteristics

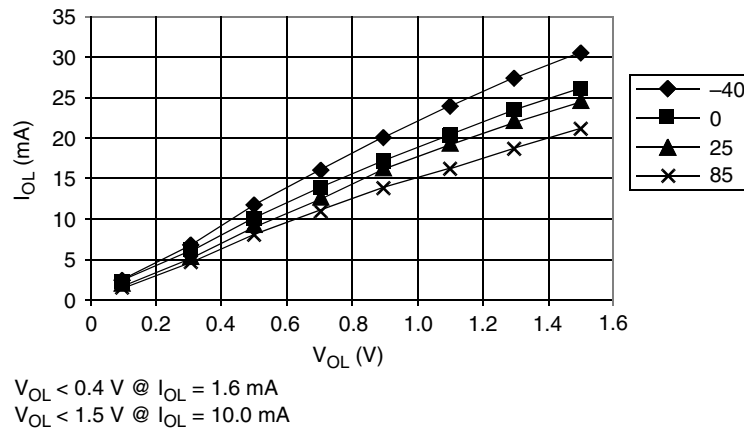


Figure 19-7. Typical Low-Side Driver Characteristics — Port PTA3–PTA0 ($V_{DD} = 5.5 \text{ Vdc}$)

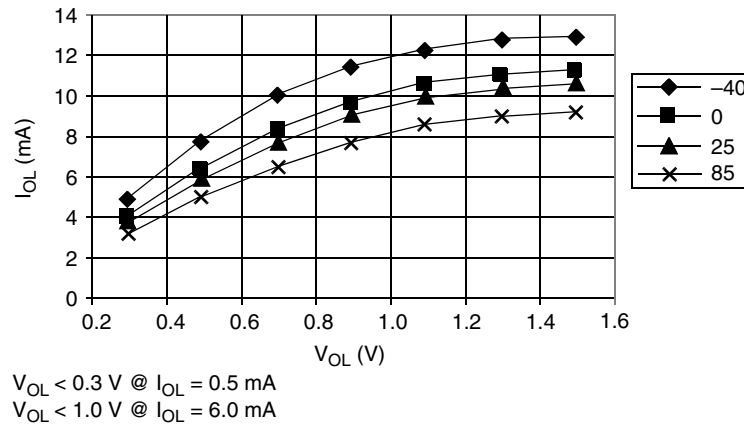


Figure 19-8. Typical Low-Side Driver Characteristics — Port PTA3–PTA0 ($V_{DD} = 2.7 \text{ Vdc}$)

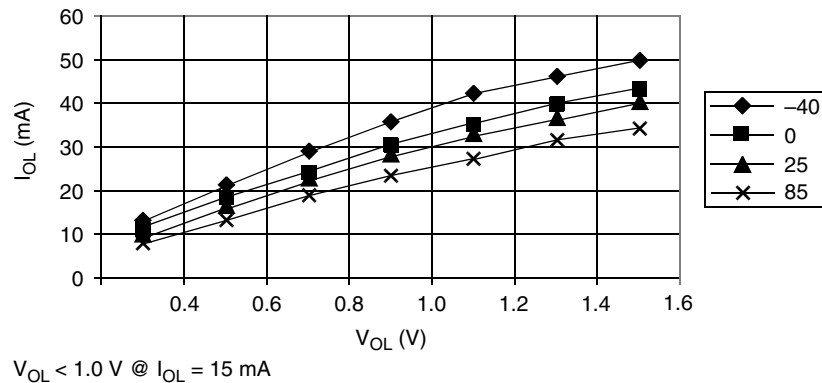


Figure 19-9. Typical Low-Side Driver Characteristics — Port PTC1–PTC0 ($V_{DD} = 4.5 \text{ Vdc}$)

Chapter 20

Ordering Information and Mechanical Specifications

20.1 Introduction

This section provides ordering information for the MC68HC908GR8A and MC68HC908GR4A along with the dimensions for:

- 32-pin low-profile quad flat pack package (case 873A)
- 28-pin dual in-line package (case 710)
- 28-pin small outline package (case 751F)

The following figures show the latest package drawings at the time of this publication. To make sure that you have the latest package specifications, contact your local Freescale Semiconductor Sales Office.

20.2 MC Order Numbers

Table 20-1. MC Order Numbers

MC Order Number	Operating Temperature Range	Package
MC68HC908GR8ACFA	−40°C to +85°C	32-pin low-profile quad flat package (LQFP)
MC68HC908GR4ACFA	−40°C to +85°C	
MC68HC908GR8AVFA	−40°C to +105°C	
MC68HC908GR8AMFA	−40°C to +125°C	
MC68HC908GR8ACP	−40°C to +85°C	28-pin dual in-line package (PDIP)
MC68HC908GR4ACP	−40°C to +85°C	
MC68HC908GR8ACDW	−40°C to +85°C	28-pin small outline package (SOIC)
MC68HC908GR4ACDW	−40°C to +85°C	

Temperature designators:
 C = −40°C to +85°C
 V = −40°C to +105°C
 M = −40°C to +125°C

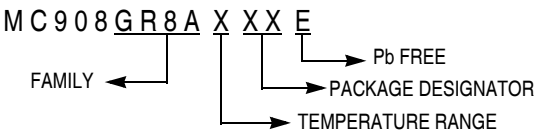
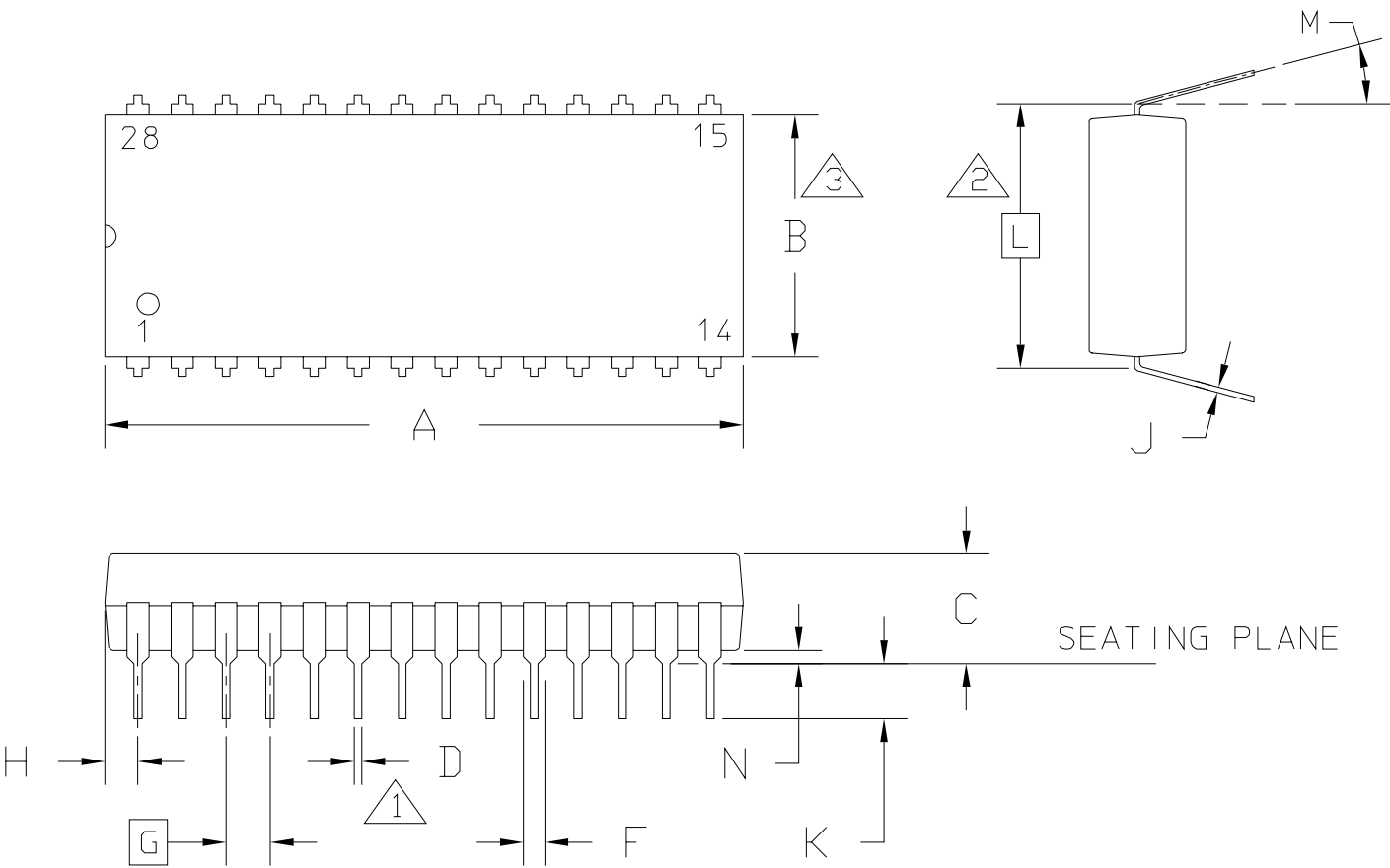


Figure 20-1. Device Numbering System

20.3 Package Dimensions

Refer to the following pages for detailed package dimensions.

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TITLE: LOW PROFILE QUAD FLAT PACK (LQFP) 32 LEAD, 0.8 PITCH (7 X 7 X 1.4)			DOCUMENT NO: 98ASH70029A		REV: C
			CASE NUMBER: 873A-04		01 APR 2005
			STANDARD: JEDEC MS-026 BBA		



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TITLE: 28 LD PDIP			DOCUMENT NO: 98ASB42390B		REV: C
			CASE NUMBER: 710-03		05 APR 2005
			STANDARD: NON-JEDEC		



NOTES:

- 1. POSITIONAL TOLERANCE OF LEADS, SHALL BE WITHIN 0.25 MM (0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
- 2. DIMENSION TO CENTER OF LEADS WHEN FORMED PARALLEL.
- 3. DIMENSION DOES NOT INCLUDE MOLD FLASH.
- 4. 710-02 OBSOLETE, NEW STD 710-03.
- 5. CONTROLLING DIMENSION: INCH

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER					
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX				
A	1.435	1.465	36.45	37.21									
B	0.540	0.560	13.72	14.22									
C	0.155	0.200	3.94	5.08									
D	0.014	0.022	0.36	0.56									
F	0.040	0.060	1.02	1.52									
G	0.100	BSC	2.54	BSC									
H	0.065	0.085	1.65	2.16									
J	0.008	0.015	0.20	0.38									
K	0.115	0.135	2.92	3.43									
L	0.600	BSC	15.24	BSC									
M	0°	15°	0°	15°									
N	0.020	0.040	0.51	1.02									
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TITLE: 28 LD PDIP										DOCUMENT NO: 98ASB42390B			REV: C
					CASE NUMBER: 710-03			05 APR 2005					
					STANDARD: NON-JEDEC								



NOTES:

- 1. DIMENSIONS ARE IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
- 3. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- 4. 751F–01 THRU –04 OBSOLETE. NEW STANDARD: 751F–05
- 5. THIS DIMENSION DOES NOT INCLUDE DAM BAR PROTRUSION ALLOWABLE DAM BAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THIS DIMENSION AT MAXIMUM MATERIAL CONDITION.

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.		MECHANICAL OUTLINE		PRINT VERSION NOT TO SCALE	
TITLE: SOIC, WIDE BODY, 28 LEAD CASEOUTLINE		DOCUMENT NO: 98ASB42345B		REV: G	
		CASE NUMBER: 751F-05		10 MAR 2005	
		STANDARD: MS-013AE			